

M3776AM8A/MCA/MFA-XXXGP

SINGLE-CHIP 16-BIT MICROCOMPUTER

REJ03B0085-0100Z Rev.1.00 2004.02.17

1. DESCRIPTION

This microcomputer is a single-chip microcomputer that adopts a high-performance silicon gate CMOS process, and is contained in a 100-pin plastic mold QFP. This single-chip microcomputer is provided with an instruction queue buffer and a data buffer for executing instructions at high speed. The central processing unit runs in a 16-bit parallel processing mode but can be converted into an 8-bit parallel processing mode when necessary. This product has been designed exclusively for video equipment system controls, incorporating a time measuring circuit for VCR servo control, a real-time pattern generating circuit, analog amplifiers, an OSD display circuit, and a data slicer, among its many other peripheral capabilities.

1.1 FEATUR	ES		
●Number of basic	instructions	3	103
Memory size	RAM	M3776AM8A-	XXXGP:2048bytes
		M3776AMCA-	XXXGP:2560bytes
		M3776AMFA-2	XXXGP:3072bytes
	ROM	M3776AM8A-	XXXGP:64kbytes
		M3776AMCA-	XXXGP:96kbytes
		M3776AMFA-	XXXGP:120kbytes
●Instruction exec	ution time		
(fastest instructi	on, 16 MHz	high-speed mode) 250 ns
(fastest instructi	on, 12 MHz	double-speed mo	de)
			167 ns
●Single power so	urce		
In 16 MHz high-	speed mode	e	
(OSD/data slice	r off)		4.0 V to 5.5 V
(OSD/data slice	r on)		4.75 V to 5.25 V
In 12 MHz doub			
(OSD/data slice	r off)		4.0 V to 5.5 V
(OSD/data slice	r on)		4.75 V to 5.25 V
In 32 kHz low-s _l	peed mode		
(OSD/data slice	r off)		2.6 V to 5.5 V
· ·			4.75 V to 5.25 V
●Interrupt			23 factors, 6 levels
●16-bit timer			3
●8-bit timer			3
●Clock-synchrono	ous serial I/C)	2
(one of which ca	an perform a	utomatic 64-byte	transfers)
●I ² C-Bus interfac	e (single ma	ster)	1
●8-bit A-D conver	ter1	unit (11 channel ir	nputs)
●8-bit D-A conver	ter		2
●12/14-bit PWM .			2
●14-bit PWM			1
●Time measurem	ent circuit (TMT)	
One counter fo	or measurir	ng time to gener	ate input signals

●Remote-control noise filter (majority of 4 samplings)

DRFG, CPFG, CPPG, VSYNG, and GEN

and RLT

●Real-time pattern (RTP) generation circuit Outputs real-time pattern to exterior, RECCTL signal to CTL head control circuit, trigger for start the A-D converter, trigger for starting OSD vertical display

One counter for measuring time to generate input signals RLS

Amplification circuits

- CTL head control circuit, CTL amplifier, CTL schmidt circuit, drum PG circuit, drum FG circuit, capstan FG circuit, capstan FG amplifier circuit
- ●Pulse duty detection circuit (VISS and VASS signal detection features embedded) Measures PBCTL signal duty ratio.
- Synchronous signal separation circuit
- ●EOR output feature (HASW, CROT)2-bit output
- Watchdog timer
- ●Programmable I/O ports69 (Ports P00-P06, P10, P11, P15-P17, P2, P4- P7, P84-P87, P9, P10, P110, P111)
- ●Input ports......10 (Ports P07, P12-P14, P30, P31, P80-P83)
- 4 Embedded clock-generating circuits Built-in feed-back resistor between XIN-XOUT Built-in feed-back resistor between XCIN-XCOUT
- ●CPU double-speed enable (f(XIN) max. 12.0 MHz)
- ●ROM correction function included
- ●OSD function

Display characters	32 characters	×16 lines
Kinds of characters	Composite Output	254 kinds
	RGB Output	285 kinds
Kinds of character sizes		8 kinds
Output method Composi	ite video signal, RGB οι	utput (PAL,
MPAL, N	ITSC, NPAL)	
Special function	. Display with backgrour	nd shadow
	(button display)	
On-chin sync correct circuit (A	AFC)	

Ann. Data Sheet A. J. com

Data slicer

On-chip slicer for XDS

1.2 APPLICATION

VCR, TVCR

Sales Strategic Planning Div. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan

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